




# Power MOSFETS


## DATASHEET


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**LM40068NHK8A**

N-Channel  
Enhancement Mode MOSFET

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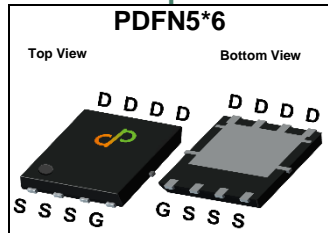


Quality Management Systems

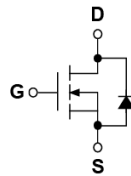
ISO 9001:2015 Certificate

## N-Channel Enhancement Mode MOSFET

### Pin Description



### Symbol



### Product Summary

| Symbol           | N-Channel | Unit       |
|------------------|-----------|------------|
| $V_{DSS}$        | 40        | V          |
| $R_{DS(ON)-Max}$ | 8.2       | m $\Omega$ |
| ID               | 50.1      | A          |

### Feature

- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

### Applications

- Power Management in DC/DC Converters

### Ordering Information

| Orderable Part Number | Package Type | Form        | Shipping           | Marking         |
|-----------------------|--------------|-------------|--------------------|-----------------|
| LM40068NHNK8A         | PDFN5*6      | Tape & Reel | 5000 / Tape & Reel | 40068<br>□□□□□□ |

Note: □□□□□□ = Lot code

### Absolute Maximum Ratings (T<sub>J</sub>=25°C Unless Otherwise Noted)

| Symbol       | Parameter                        | N-Channel               | Unit               |    |
|--------------|----------------------------------|-------------------------|--------------------|----|
| $V_{DSS}$    | Drain-Source Voltage             | 40                      | V                  |    |
| $V_{GSS}$    | Gate-Source Voltage              | ±20                     |                    |    |
| $T_J$        | Maximum Junction Temperature     | 175                     | °C                 |    |
| $T_{STG}$    | Storage Temperature Range        | -55 to 175              | °C                 |    |
| $I_S$        | Diode Continuous Forward Current | $T_C=25^\circ\text{C}$  | 24.4               | A  |
| $I_{DM}$     | Pulse Drain Current Tested       | $T_C=25^\circ\text{C}$  | 125.3 <sup>①</sup> | A  |
| $I_D$        | Continuous Drain Current         | $T_C=25^\circ\text{C}$  | 50.1               | A  |
|              |                                  | $T_C=100^\circ\text{C}$ | 35.4               |    |
| $P_D$        | Maximum Power Dissipation        | $T_C=25^\circ\text{C}$  | 37.5               | W  |
|              |                                  | $T_C=100^\circ\text{C}$ | 18.8               |    |
| $I_D^{②}$    | Continuous Drain Current         | $T_A=25^\circ\text{C}$  | 12.4               | A  |
|              |                                  | $T_A=70^\circ\text{C}$  | 10.4               |    |
| $P_D^{②}$    | Maximum Power Dissipation        | $T_A=25^\circ\text{C}$  | 2.3                | W  |
|              |                                  | $T_A=70^\circ\text{C}$  | 1.6                |    |
| $I_{AS}^{③}$ | Avalanche Current, Single pulse  | L=0.1mH                 | 20                 | A  |
|              |                                  | L=0.5mH                 | 11                 | A  |
| $E_{AS}^{③}$ | Avalanche Energy, Single pulse   | L=0.1mH                 | 20                 | mJ |
|              |                                  | L=0.5mH                 | 30                 |    |

### Thermal Characteristics

| Symbol              | Parameter                              | Rating       | Unit |      |
|---------------------|--|--------------|------|------|
| $R_{\theta JC}$     | Thermal Resistance-Junction to Case    | Steady State | 4    | °C/W |
| $R_{\theta JA}^{②}$ | Thermal Resistance-Junction to Ambient | Steady State | 65   | °C/W |

Note ① : Max. current is limited by junction temperature

Note ② : Surface Mounted on 1in<sup>2</sup> FR-4 board with 1oz.

Note ③ : UIS tested and pulse width are limited by maximum junction temperature 175°C.

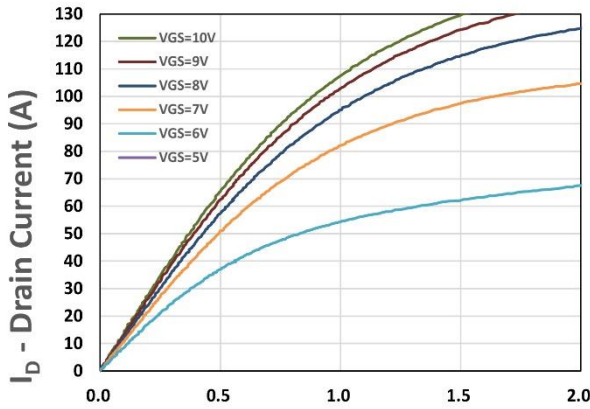
## N-Channel Electrical Characteristics (T<sub>J</sub>=25°C Unless Otherwise Noted)

| Symbol                                     | Parameter                        | Test Conditions  | Min. | Typ. | Max. | Unit |
|--|----------------------------------|--|------|------|------|------|
| <b>Static Electrical Characteristics</b>   |                                  |  |      |      |      |      |
| <b>BV<sub>DSS</sub></b>                    | Drain-Source Breakdown Voltage   | V <sub>GS</sub> =0V, I <sub>DS</sub> =250uA  | 40   | -    | -    | V    |
| <b>I<sub>DSS</sub></b>                     | Zero Gate Voltage Drain Current  | V <sub>DS</sub> =32V, V <sub>GS</sub> =0V  | -    | -    | 1    | uA   |
| <b>V<sub>GS(th)</sub></b>                  | Gate Threshold Voltage           | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250uA                            | 2    | 3    | 4    | V    |
| <b>I<sub>GSS</sub></b>                     | Gate Leakage Current             | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V   | -    | -    | ±100 | nA   |
| <b>R<sub>DS(ON)</sub><sup>④</sup></b>      | Drain-Source On-state Resistance | V <sub>GS</sub> =10V, I <sub>DS</sub> =15A   | -    | 6.8  | 8.2  | mΩ   |
| <b>gfs</b>                                 | Forward Transconductance         | V <sub>DS</sub> =5V, I <sub>DS</sub> =10A  | -    | 9.4  | -    | S    |
| <b>Dynamic Characteristics<sup>⑤</sup></b> |                                  |  |      |      |      |      |
| <b>R<sub>G</sub></b>                       | Gate Resistance                  | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, Freq.=1MHz                                 | -    | 1.8  | -    | Ω    |
| <b>C<sub>iSS</sub></b>                     | Input Capacitance                | V <sub>GS</sub> =0V, V <sub>DS</sub> =20V, Freq.=1MHz                                | -    | 715  | -    | pF   |
| <b>C<sub>oss</sub></b>                     | Output Capacitance               |  | -    | 222  | -    |      |
| <b>C<sub>rSS</sub></b>                     | Reverse Transfer Capacitance     |  | -    | 21   | -    |      |
| <b>t<sub>d(ON)</sub></b>                   | Turn-on Delay Time               | V <sub>GS</sub> =10V, V <sub>DS</sub> =20V, I <sub>D</sub> =1A, R <sub>GEN</sub> =1Ω | -    | 8    | -    | nS   |
| <b>t<sub>r</sub></b>                       | Turn-on Rise Time                |  | -    | 9    | -    |      |
| <b>t<sub>d(OFF)</sub></b>                  | Turn-off Delay Time              |  | -    | 13   | -    |      |
| <b>t<sub>f</sub></b>                       | Turn-off Fall Time               |  | -    | 15   | -    |      |
| <b>Q<sub>g</sub></b>                       | Total Gate Charge                | V <sub>GS</sub> =6V, V <sub>DS</sub> =20V, I <sub>D</sub> =15A                       | -    | 5.8  | -    | nC   |
| <b>Q<sub>g</sub></b>                       | Total Gate Charge                | V <sub>GS</sub> =10V, V <sub>DS</sub> =20V, I <sub>D</sub> =15A                      | -    | 9.4  | -    |      |
| <b>Q<sub>gs</sub></b>                      | Gate-Source Charge               |  | -    | 3.5  | -    |      |
| <b>Q<sub>gd</sub></b>                      | Gate-Drain Charge                |  | -    | 1    | -    |      |
| <b>Source-Drain Characteristics</b>        |                                  |  |      |      |      |      |
| <b>V<sub>SD</sub><sup>④</sup></b>          | Diode Forward Voltage            | I <sub>SD</sub> =20A, V <sub>GS</sub> =0V  | -    | 0.8  | 1.1  | V    |
| <b>t<sub>rr</sub></b>                      | Reverse Recovery Time            | I <sub>F</sub> =7.5A, V <sub>R</sub> =20V  | -    | 16   | -    | nS   |
| <b>Q<sub>rr</sub></b>                      | Reverse Recovery Charge          | di <sub>F</sub> /dt=100A/μs  | -    | 6    | -    | nC   |

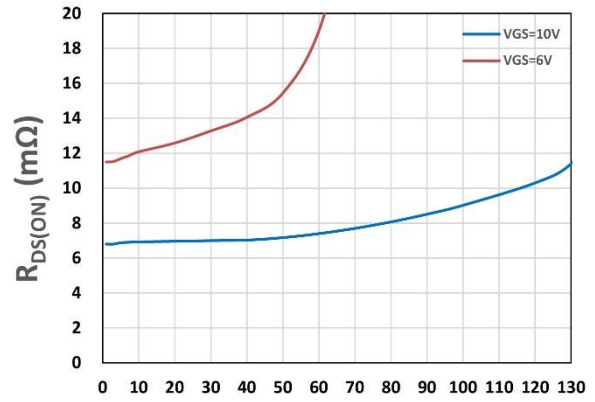
Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

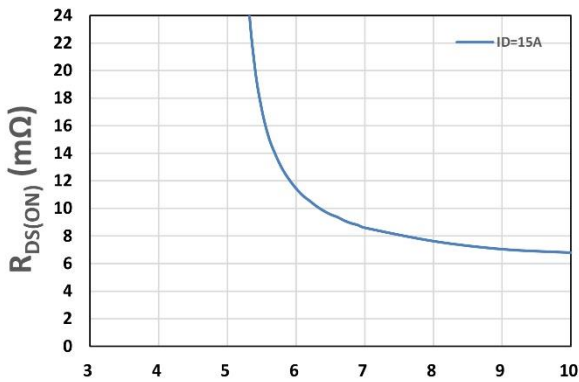
## N-Channel Typical Characteristics



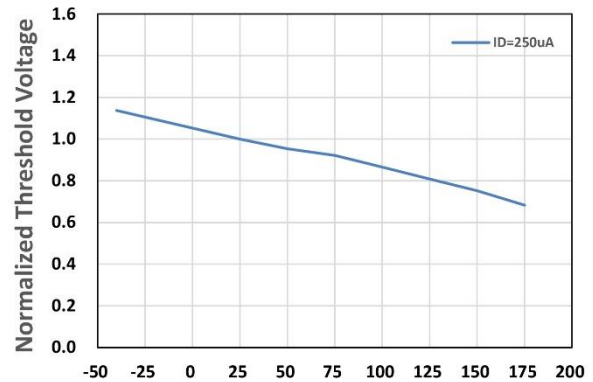
**$V_{DS}$  - Drain - Source Voltage (V)**  
Figure 1. Output Characteristics



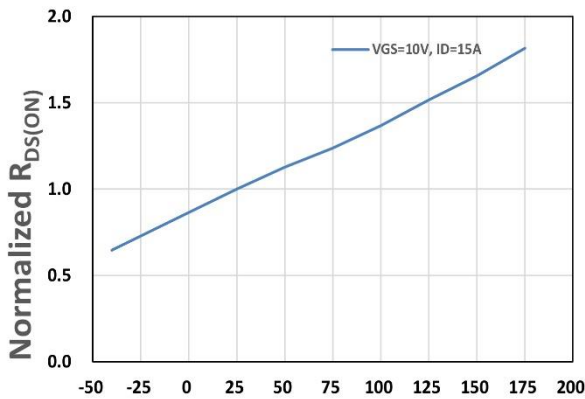
**$I_D$  - Drain Current (A)**  
Figure 2. On-Resistance vs.  $I_D$



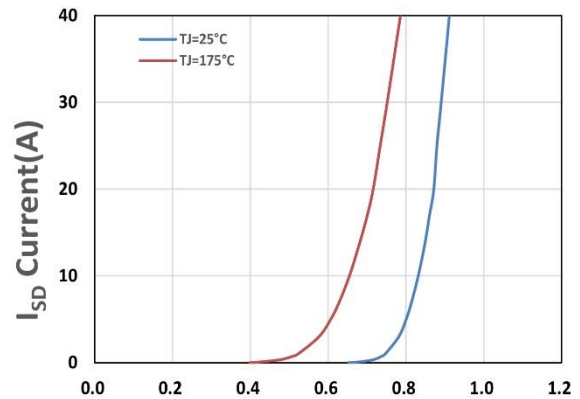
**$V_{GS}$  - Gate - Source Voltage (V)**  
Figure 3. On-Resistance vs.  $V_{GS}$



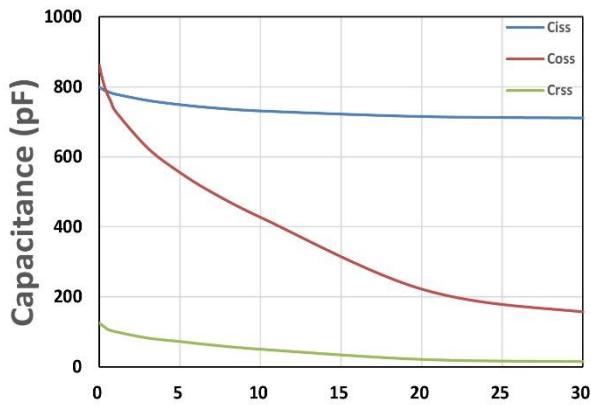
**$T_j$ , Junction Temperature ( $^{\circ}C$ )**  
Figure 4. Gate Threshold Voltage



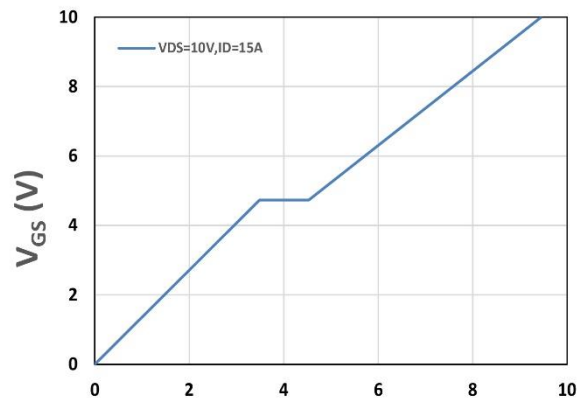
**$T_j$ , Junction Temperature ( $^{\circ}C$ )**  
Figure 5. Drain-Source On Resistance



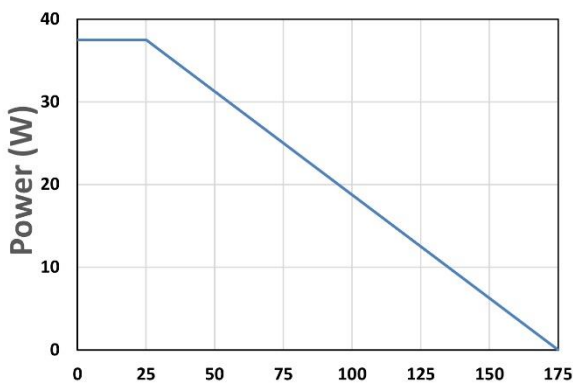
**$V_{SD}$ , Source-Drain Voltage (V)**  
Figure 6. Source-Drain Diode Forward



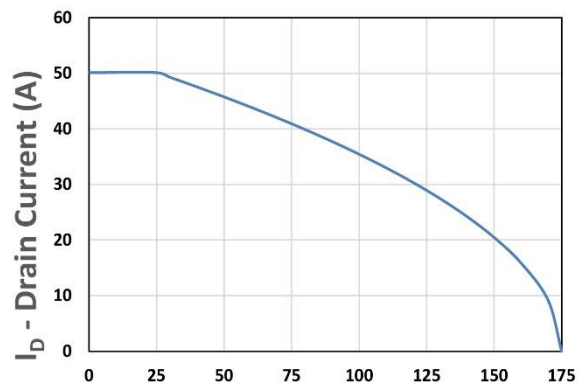
**V<sub>DS</sub> - Drain - Source Voltage (V)**  
Figure 7. Capacitance



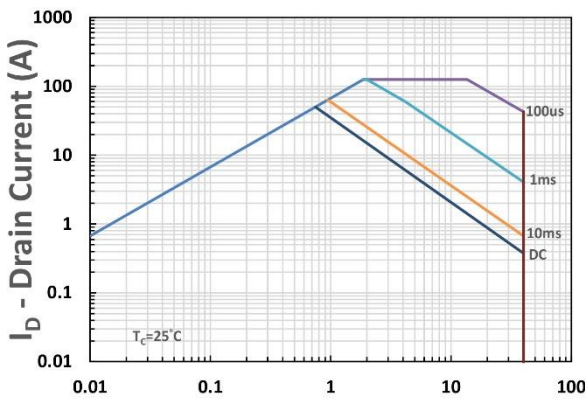
**Qg, Total Gate Charge (nC)**  
Figure 8. Gate Charge Characteristics



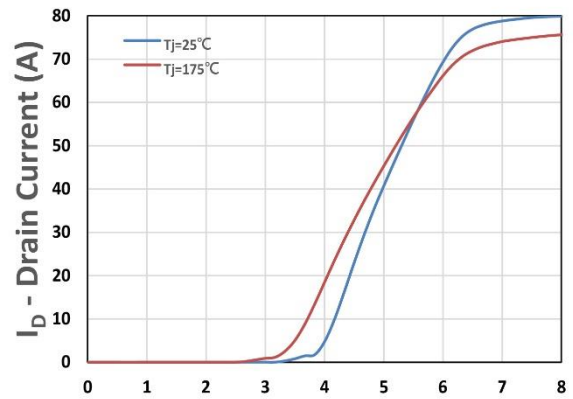
**T<sub>c</sub>-Case Temperature (°C)**  
Figure 9. Power Dissipation



**T<sub>c</sub>-Case Temperature (°C)**  
Figure 10. Drain Current



**V<sub>DS</sub> - Drain-Source Voltage (V)**  
Figure 11. Safe Operating Area



**V<sub>GS</sub> - Gate - Source Voltage (V)**  
Figure 12. Transfer Characteristics

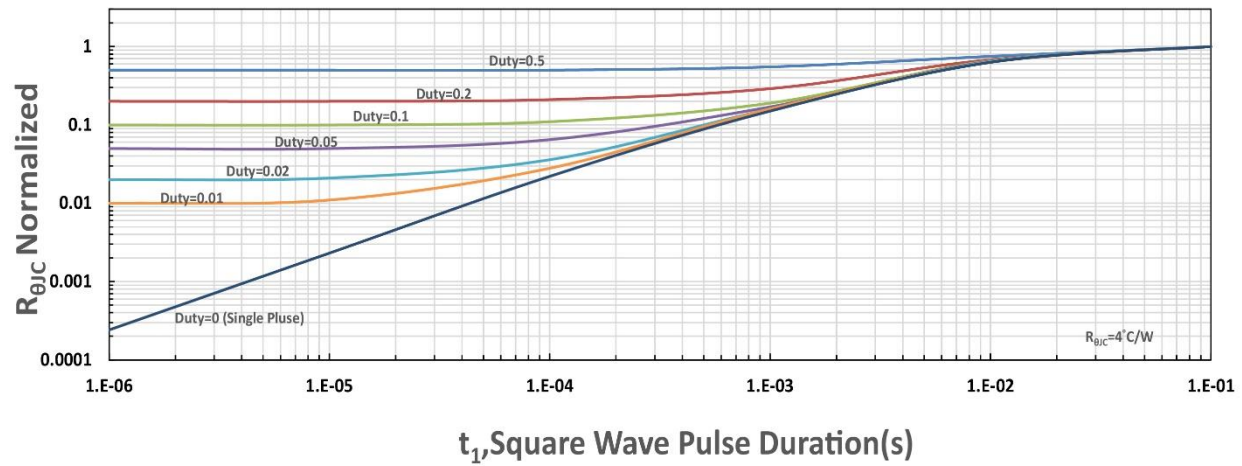


Figure 13.  $R_{\theta JC}$  Transient Thermal Impedance